

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHIN HARADA	08/16/2012
SHINSUKE FUJIWARA	08/07/2012
TARO NISHIGUCHI	08/08/2012
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<b>State/Country:</b>	JAPAN
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14978866
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<b>ATTORNEY DOCKET NUMBER:</b>	201917-0086-01-US-536523
<b>NAME OF SUBMITTER:</b>	JOHN G. SMITH
<b>SIGNATURE:</b>	/John G. Smith/
<b>DATE SIGNED:</b>	12/22/2015
<b>Total Attachments: 2</b>	
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source=201917_0086_01_536523_Assignfiled20151222#page2.tif	

ATTORNEY DOCKET NO.:

SOLE/JOINT INVENTION  
(U.S. Rights Only)

### ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

Silicon Carbide Substrate and Method of Manufacturing the Same

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_\_); and

WHEREAS, Sumitomo Electric Industries, Ltd., a corporation of Japan, whose post office address is 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 541-0041 Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

<b>Full Name of Sole or First Assignor</b> Shin HARADA	<b>Assignor's Signature</b> <i>Shin Harada</i>	<b>Date</b> August 16, 2012
<b>Address</b> c/o Osaka Works of Sumitomo Electric Industries, Ltd., 1-3, Shimaya 1-chome, Konohana-ku, Osaka-shi, Osaka 554-0024 Japan		<b>Citizenship</b> Japanese
<b>Full Name of Second Assignor</b> Shinsuke FUJIWARA	<b>Assignor's Signature</b> <i>Shinsuke Fujiwara</i>	<b>Date</b> August 7, 2012
<b>Address</b> c/o Itami Works of Sumitomo Electric Industries, Ltd., 1-1, Koyakita 1-chome, Itami-shi, Hyogo 664-0016 Japan		<b>Citizenship</b> Japanese
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

## ATTORNEY DOCKET NO.:

<b>Full Name of Third Assignor</b> Taro NISHIGUCHI	Assignor's Signature <i>Taro Nishiguchi</i>	Date <i>August 8 2012</i>
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Address		Citizenship
<b>Full Name of Fifth Assignor</b>	Assignor's Signature	Date
Address		Citizenship
<b>Full Name of Sixth Assignor</b>	Assignor's Signature	Date
Address		Citizenship
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Address		Citizenship
<b>Full Name of Eighth Assignor</b>	Assignor's Signature	Date
Address		Citizenship
<b>Full Name of Ninth Assignor</b>	Assignor's Signature	Date
Address		Citizenship
<b>Full Name of Tenth Assignor</b>	Assignor's Signature	Date
Address		Citizenship
<b>Full Name of Eleventh Assignor</b>	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		